

PATENT ABSTRACTS OF JAPAN

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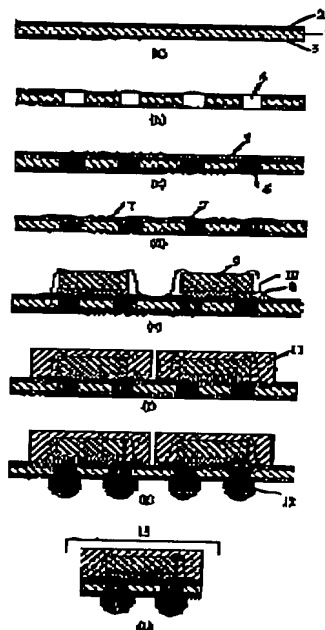
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(54) SEMICONDUCTOR PACKAGE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor package adaptable for reducing the size and increasing the density of the package.

SOLUTION: A semiconductor package has a board for mounting a semiconductor chip 9 on an insulation board, interconnection pattern 7 electrically connected to semiconductor chip electrodes formed on one side of the board, external connection terminals 12 formed on the other side of the board 1, and layer interconnection 6 connecting the pattern 7 to the terminals 12. The substrate is formed so that the end part of the pattern connected to the interconnection 6 may be within a plane region exposed of the interconnection 6.



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